

Materials List for:

High Throughput Microfluidic Rapid and Low Cost Prototyping Packaging Methods

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Materials

Name	Company	Catalog Number	Comments
Epoxy 731	Epotek	731	
PDMS	Dow Corning	SYLGARD 184	
UV Epoxy	Epotek	OG159	
Micropump	Harvard Apparatus	PHD Ultra	
PCB	Advanced Circuits		
Plexiglass	Ecole Polytechnique		
Adhesive conductive film	3M	9703	